



CT817 Series DC Input 4-Pin DMC-Isolator® Phototransistor Optocoupler

Features

- High isolation 5000 VRMS
- Patented coplanar structure DMC-Isolator®
- Various CTR selection available
- DC input with transistor output
- Operating Temperature range - 55 °C to 110 °C
- External creepage distance $\geq 7.0\text{mm}$
- Distance Through Isolation $\geq 0.4\text{mm}$
- Clearances Distance $\geq 7.5\text{mm}$ (S/SL Type)
- Clearances Distance $\geq 8.0\text{mm}$ (M/SLM Type)
- RoHS and REACH compliance
- Halogen Free compliance (Optional)
- MSL class 1
- Regulatory Approvals
 - ✓ UL - UL1577 (E364000)
 - ✓ VDE - EN60747-5-5(VDE0884-5)
 - ✓ CQC – GB4943.1, GB8898 (14001104781)
 - ✓ IEC62368 (FI/41119)

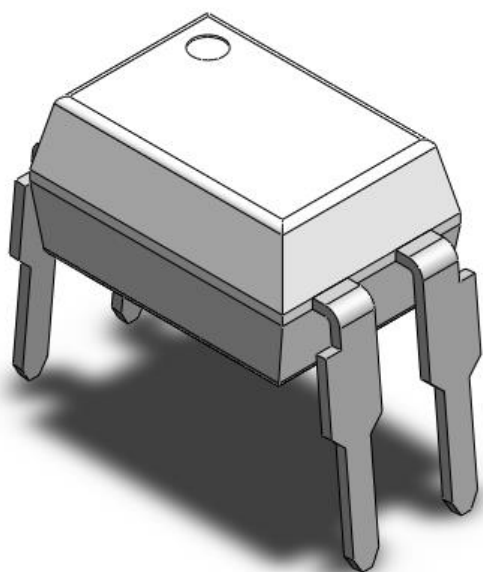
Description

The CT817 series consists of a photo transistor optically coupled to an Infrared-emitting diode in a 4-lead DIP DMC-Isolator® package with different lead forming options.

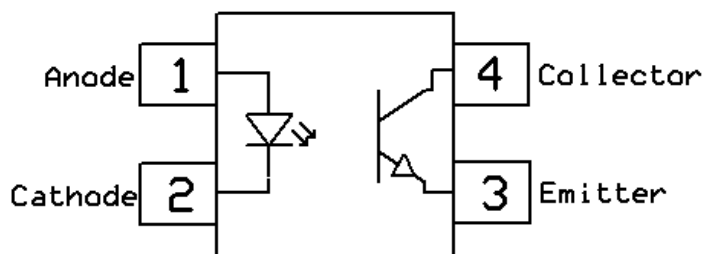
Applications

- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Package Outline



Schematic



Note: Different lead forming options available. See package dimension.



CT817 Series

DC Input 4-Pin DMC-Isolator®

Phototransistor Optocoupler

Absolute Maximum Ratings $T_A = 25^{\circ}\text{C}$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
V _{ISO}	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	5000	V _{RMS}	
T _{OPR}	Operating temperature	-55 ~ +110	°C	
T _{STG}	Storage temperature	-55 ~ +150	°C	
T _{SOL}	Soldering temperature (For 10 seconds)	260	°C	
P _{TOT}	Total power dissipation	200	mW	
Emitter				
I _F	Forward current	60	mA	
I _{F(TRANS)}	Peak transient current (≤1μs P.W,300pps)	1	A	
V _R	Reverse voltage	6	V	
P _D	Emitter power dissipation	100	mW	
R _{thJ-A}	Thermal Resistance Junction-Ambient	350	°C/W	
T _J	Junction temperature	125	°C	
Detector				
P _D	Detector power dissipation	150	mW	
B _{VCEO}	Collector-Emitter Breakdown Voltage	35	V	
B _{VECO}	Emitter-Collector Breakdown Voltage	6	V	
I _C	Collector Current	50	mA	



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Electrical Characteristics $T_A = 25^\circ\text{C}$, unless otherwise specified

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	$I_F = 10\text{mA}$	-	1.24	1.4	V	
I_R	Reverse Current	$V_R = 6\text{V}$	-	-	5	μA	
C_{IN}	Input Capacitance	$f = 1\text{MHz}$	-	10	30	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$B_{V_{CEO}}$	Collector-Emitter Breakdown	$I_C = 0.1\text{mA}$	35	-	-	V	
$B_{V_{ECO}}$	Emitter-Collector Breakdown	$I_E = 0.1\text{mA}$	6	-	-	V	
I_{CEO}	Collector-Emitter Dark Current	$V_{CE} = 20\text{V}$, $I_F = 0\text{mA}$	-	-	100	nA	

Transfer Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes	
CTR	Current Transfer Ratio	$I_F = 5\text{mA}$, $V_{CE} = 5\text{V}$	CT817	50	-	600	%	
			CT817A	80	-	160		
			CT817B	130	-	260		
			CT817C	200	-	400		
			CT817D	300	-	600		
$V_{CE(SAT)}$	Collector-Emitter Saturation Voltage	$I_F = 20\text{mA}$, $I_C = 1\text{mA}$	-	0.1	0.2	V		
R_{IO}	Isolation Resistance	$V_{IO} = 500\text{V}_{DC}$, 40 ~ 60% R.H.	5×10^{10}	-	-	Ω		
C_{IO}	Isolation Capacitance	$f = 1\text{MHz}$	-	0.25	1	pF		

Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
t_r	Rise Time	$I_C = 2\text{mA}$, $V_{CE} = 2\text{V}$ $R_L = 100\Omega$	-	6	18	μs	
t_f	Fall Time		-	8	18		



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Typical Characteristic Curves $T_A = 25^\circ\text{C}$, unless otherwise specified

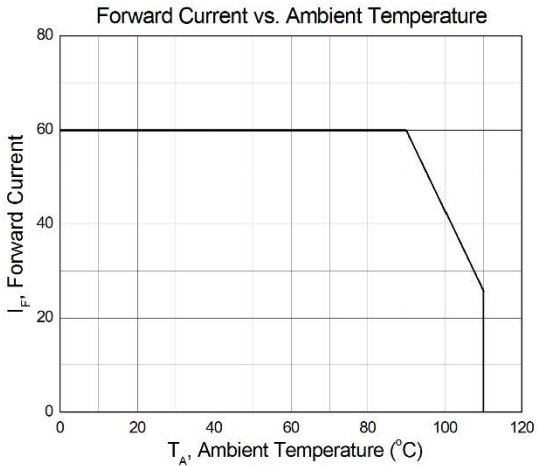


Figure 1

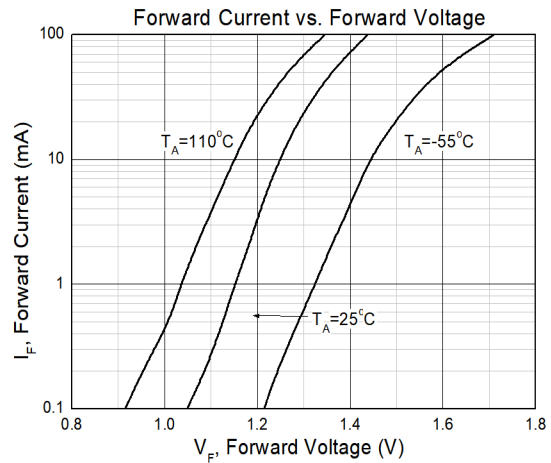


Figure 1

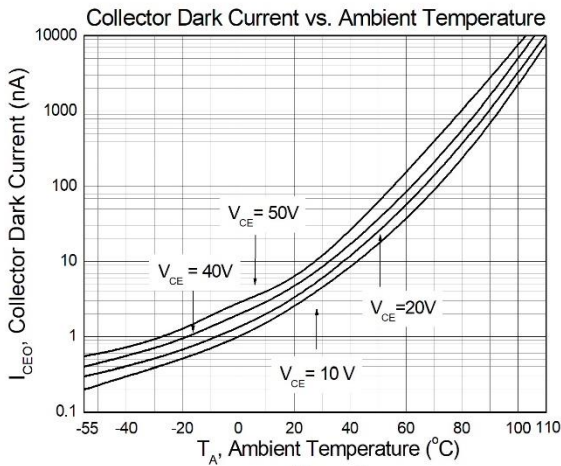


Figure 3

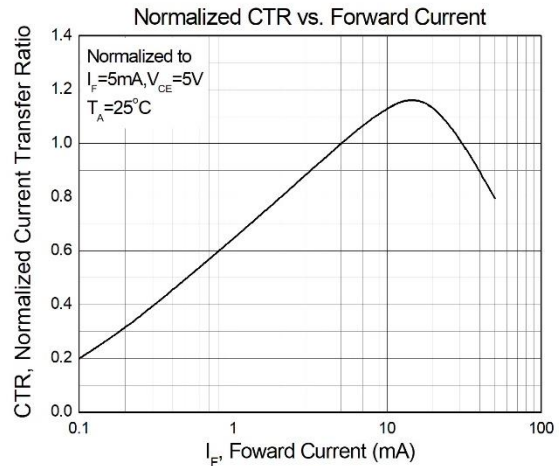


Figure 4

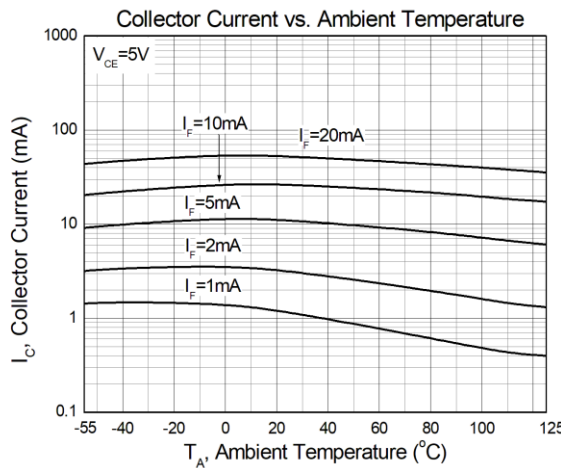


Figure 5

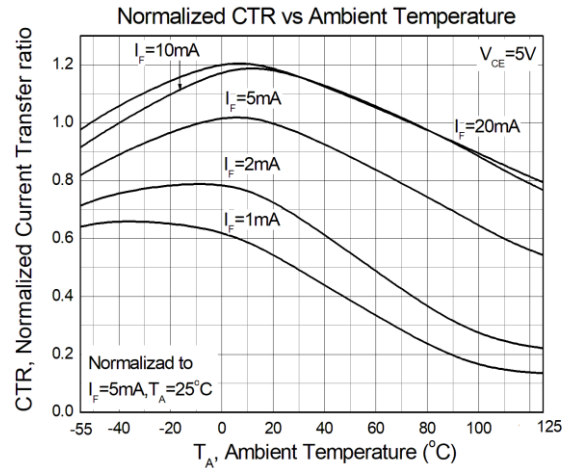


Figure 6



Typical Characteristic Curves $T_A = 25^\circ\text{C}$, unless otherwise specified (Continued)

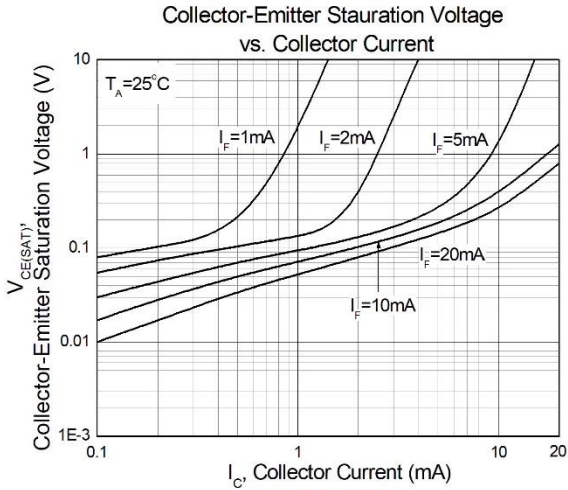


Figure 7

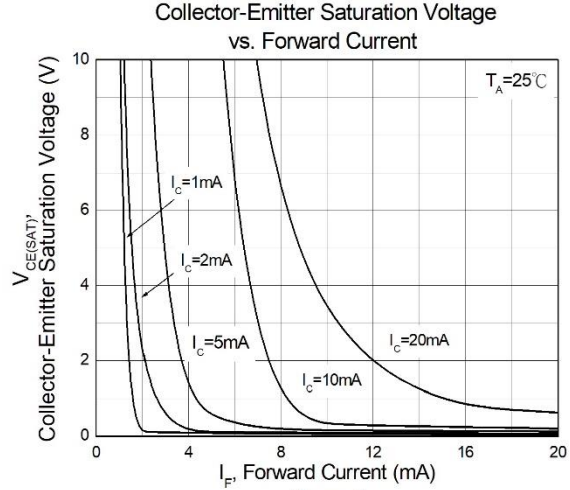


Figure 8

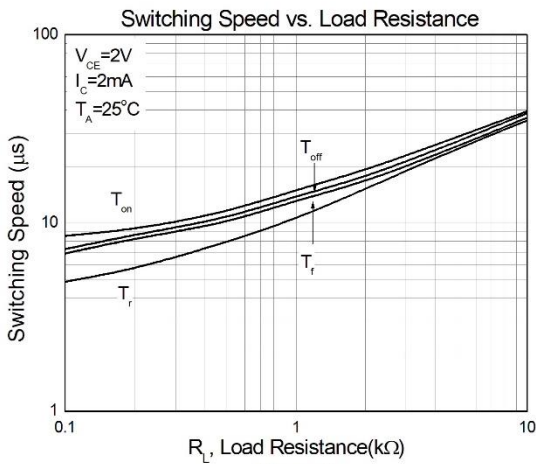


Figure 9

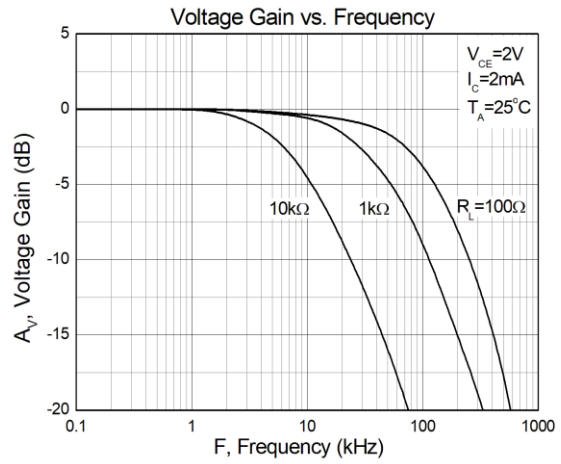


Figure 10



Test Circuit

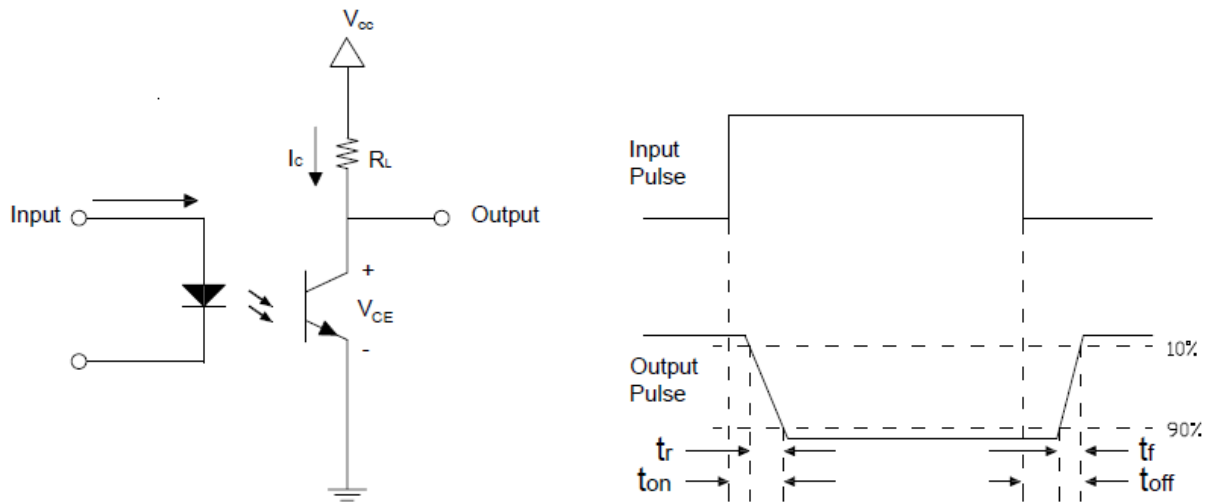
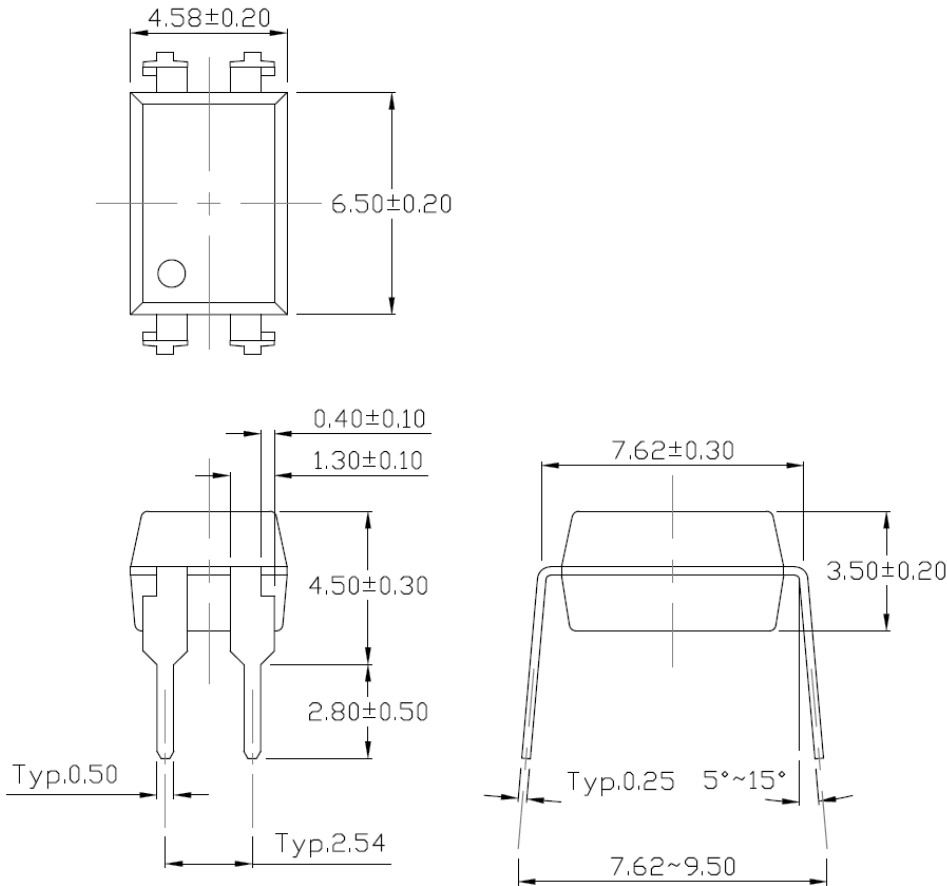


Figure 11: Switching Time Test Circuits

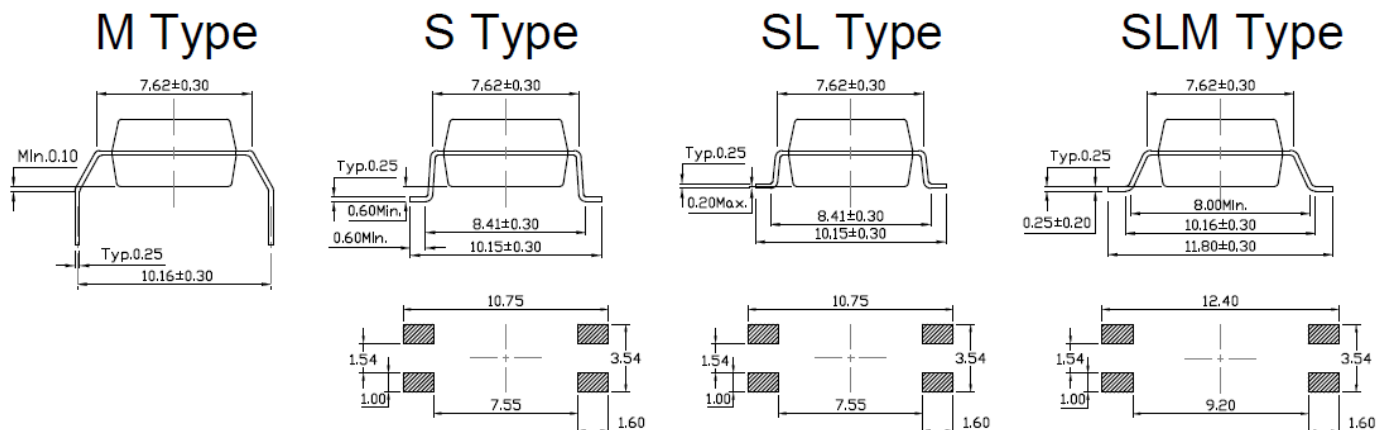


Package Dimension *Dimensions in mm unless otherwise stated*

Standard DIP – Through Hole



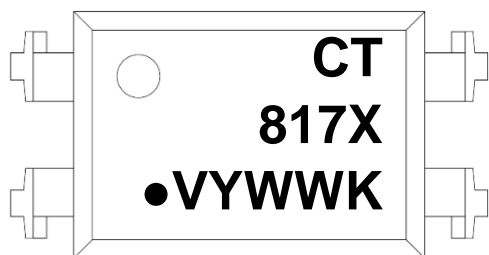
Forming Option *Dimensions in mm unless otherwise stated*





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Marking Information



Note:

- CT : Denotes “CT Micro”
- 817 : Part Number
- X : CTR Rank Option (Blank, A, B, C or D)
- V : VDE Safety Mark Option (Blank or V)
- Y : One Digit Year Code
- WW : Two Digit Work Week
- K : Manufacturing Code
- : Lead Frame Material Option
(Blank : Iron ; • : Copper)

Ordering Information

CT817X (V)(Y)(Z)-HG

- CT = Denotes “CT Micro”
- 817 = Part Number
- X = CTR Rank Option (Blank, A, B, C, D, I, J, K, N, F or Y)
- V = VDE Safety Mark Option (Blank or V)
- Y = Lead Form Option (S, SL, M, SLM or Blank)
- Z = Tape and Reel Option (Blank, T1, T2, T3 or T4)
- H = Lead Frame Option (H: Iron, Blank: Copper)
- G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

Option	Description	Quantity
None	Standard 4 Pin DIP	100 Units/Tube
M	Gullwing (400mil) Lead Forming	100 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1500 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1500 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1500 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1500 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	1500 Units/Reel
SLM(T2)	Surface Mount (Gullwing) Lead Forming – With Option 2 Taping	1500 Units/Reel

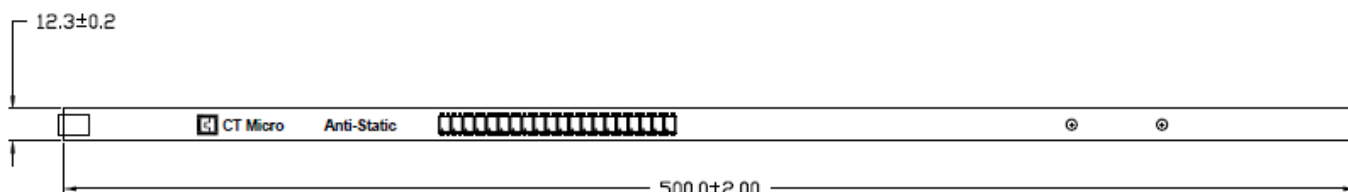


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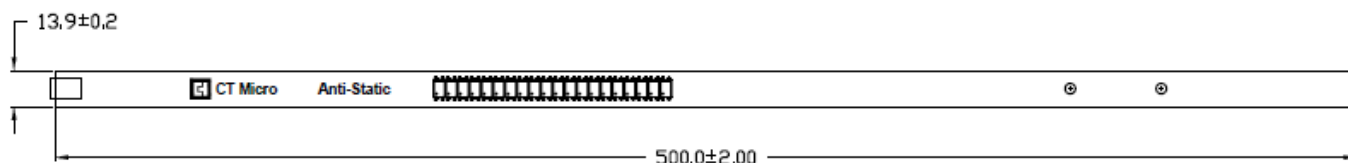
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Carrier Specifications *Dimensions in mm unless otherwise stated*

Tube Option Standard DIP

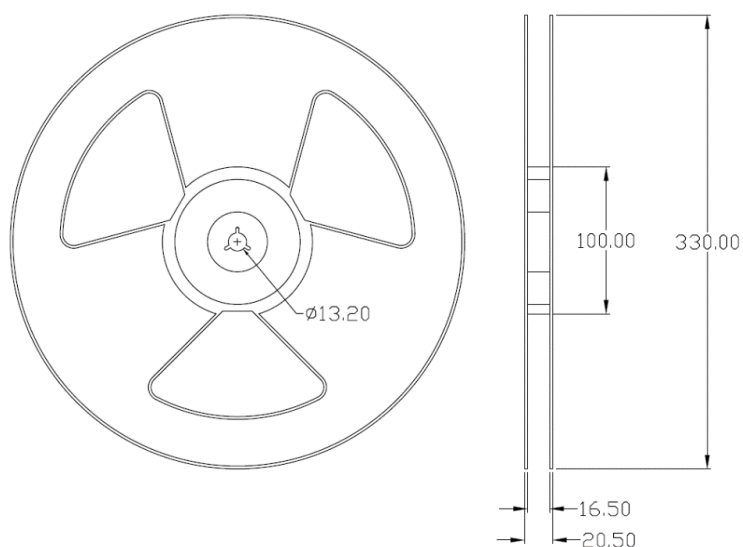


Tube Option M Type

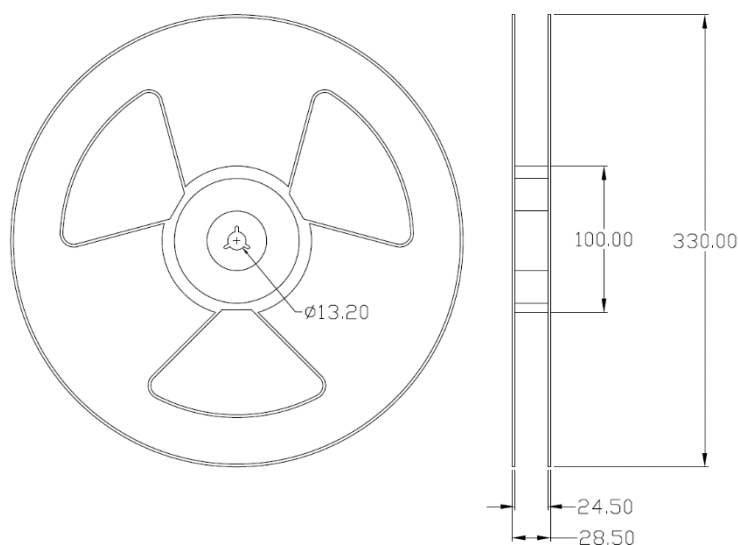


Reel Dimension *All dimensions are in mm, unless otherwise stated*

Option S(T1/T2) & SL(T1/T2)



Option SLM(T1/T2)

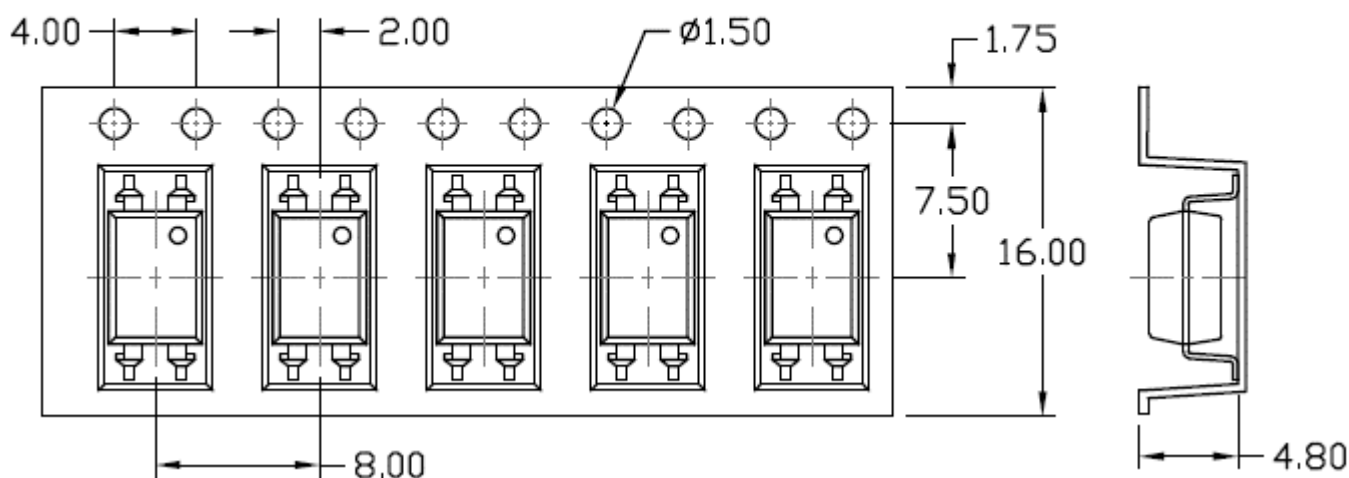




Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

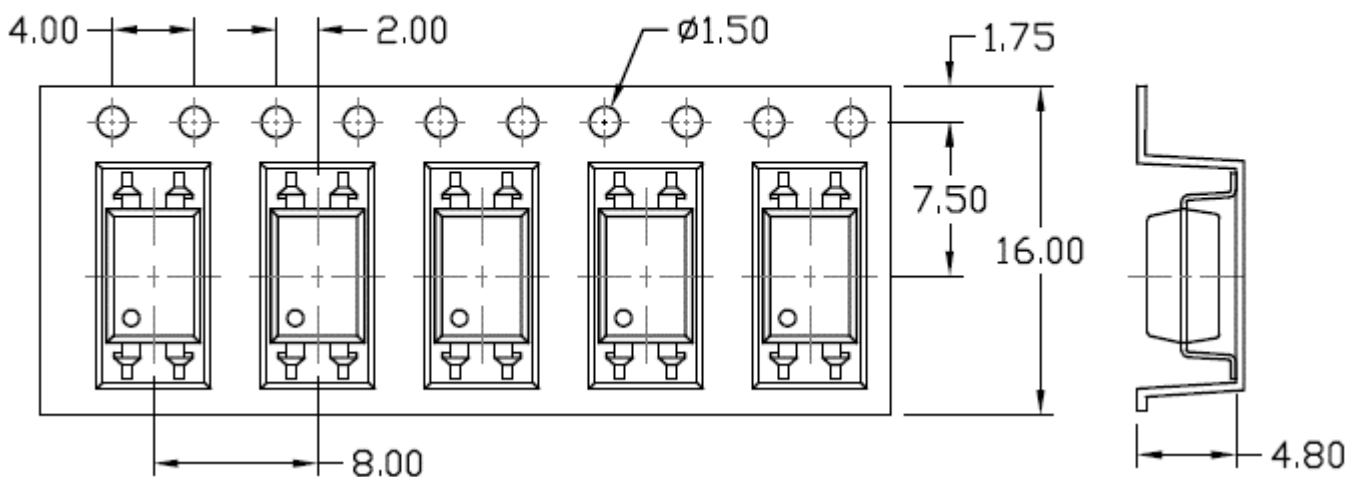
Option S(T1) & SL(T1)

Input Direction →



Option S(T2) & SL(T2)

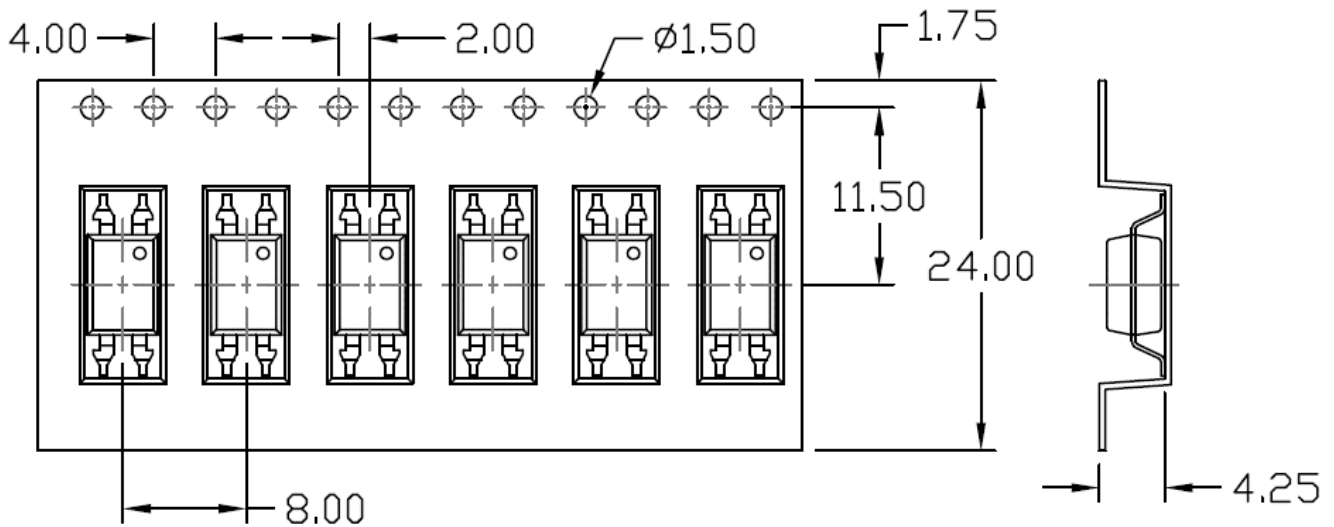
Input Direction →





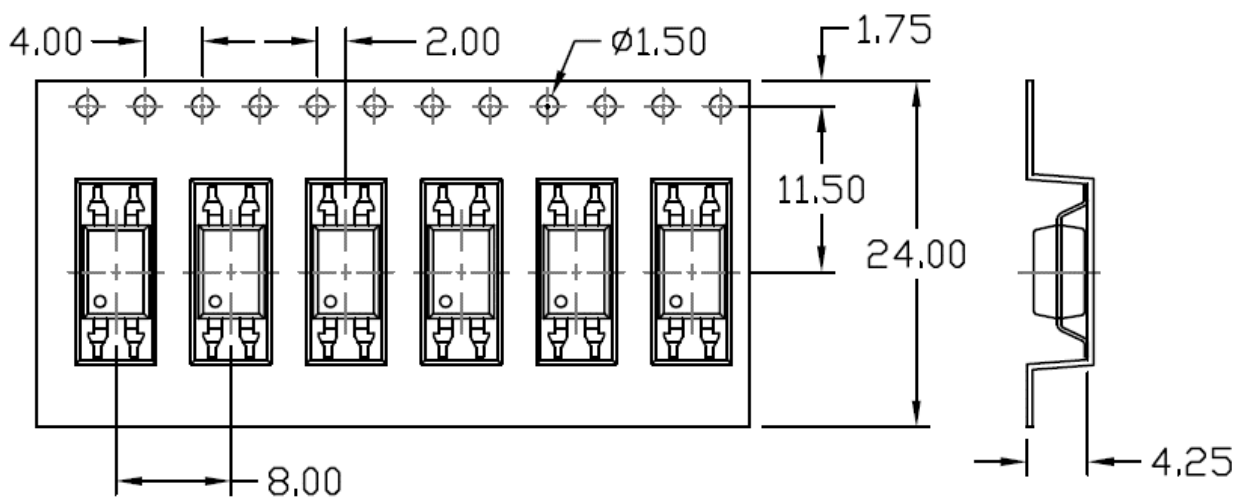
Option SLM(T1)

Input Direction



Option SLM(T2)

Input Direction





Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

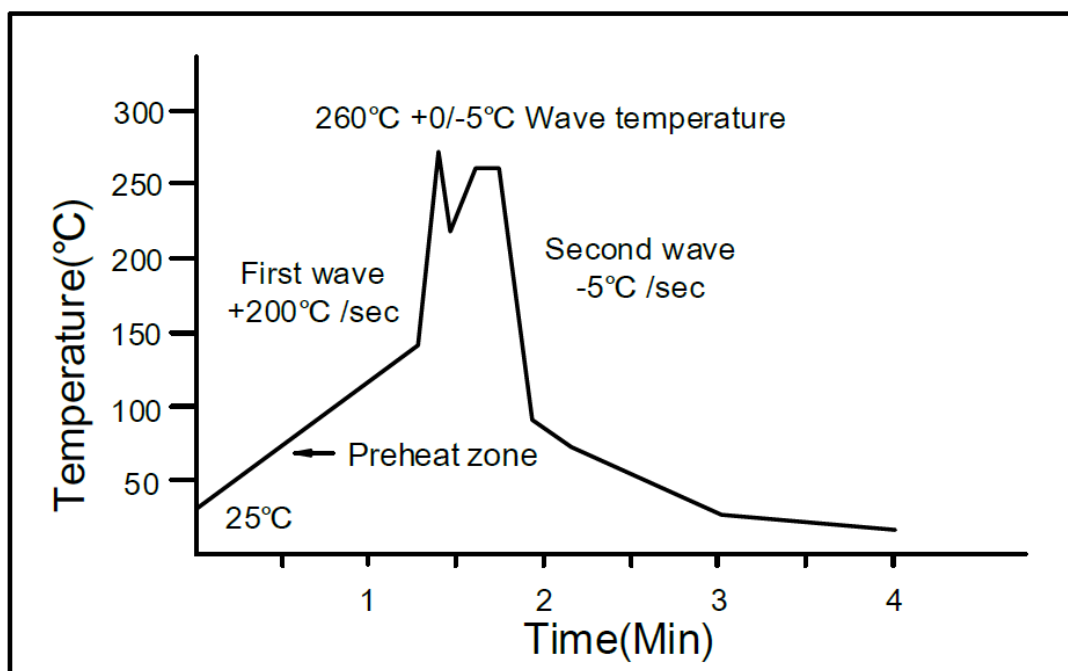
One time soldering is recommended within the condition of temperature.

Temperature: $260 \pm 0/-5^\circ\text{C}$.

Time: 10 sec.

Preheat temperature: 25 to 140°C .

Preheat time: 30 to 80 sec.



Iron soldering (Follow the standard MIL-STD 202G, Method 210F)

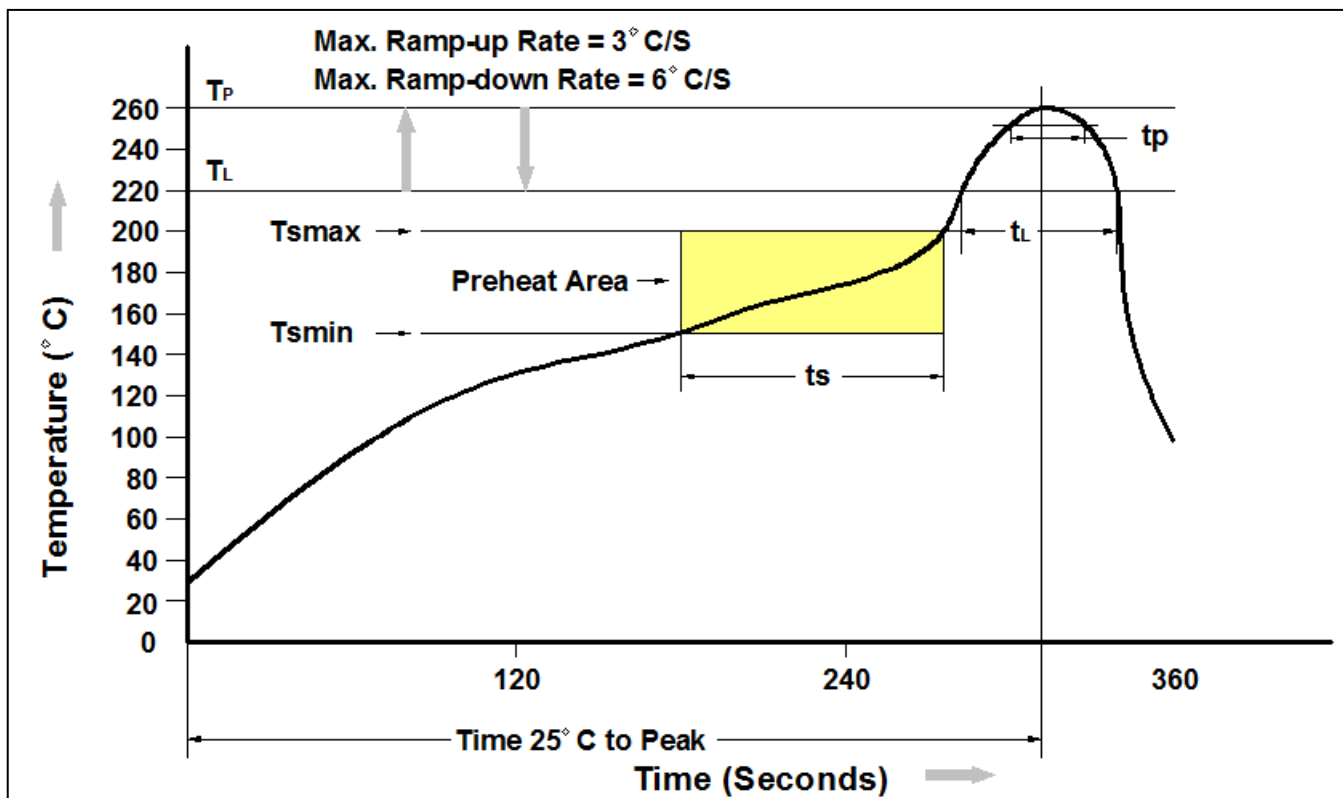
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: $350 \pm 10^\circ\text{C}$

Time: 5 sec max.



Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



CT817 Series DC Input 4-Pin DMC-Isolator® Phototransistor Optocoupler

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